

YAO-4337US

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Hideki Kuwajima et al. : Art Unit: 2651
Serial No.: 09/774,347 : Examiner:
Filed: January 31, 2001 :
For: HEAD SUPPORT MECHANISM AND :
THIN FILM PIEZOELECTRIC ACTUATOR

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INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

S I R :

Pursuant to 37 C.F.R. §§ 1.97 and 1.98 and to the duty of disclosure set forth in 37 C.F.R. § 1.56, the Examiner in charge of the above-identified application is requested to consider and make of record the references listed on the PTO 1449 (R&P) submitted herewith. A copy of each of the listed references is also enclosed.

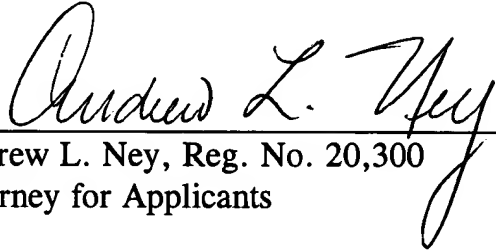
Although the information submitted herewith may be "material" to the Examiner's consideration of the subject application, this submission is not intended to constitute an admission that such information is "prior art" as to the claimed invention.

In accordance with 37 C.F.R. § 1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made.

Japanese Reference Nos. 5-47126 and 9-265738 are not in the English language but an English abstract thereof is attached to each reference submitted herewith.

This information disclosure statement is being filed within three months of the filing date of the above-referenced application. No Fee or certification is required. 37 C.F.R. § 1.97(b).

Respectfully submitted,



Andrew L. Ney, Reg. No. 20,300
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Enclosures:

PTO Form 1449
(3) References

Dated: April 10, 2001

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The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 18-0350 of any fees associated with this communication.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, with sufficient postage, in an envelope addressed to:
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